

IN THE SPECIFICATION:

Page 14, please amend paragraph [0061] starting on line 6 and ending on line 8 of the specification as follows:

[0061] A handling means 32 (see Figure 20), with which the stack of storage rings can be opened in a selective manner, can be controlled via a control panel 30. In the exemplary embodiment shown here, this happens by means of a tool 50 coordinated with the device.

Page 15, please amend paragraph [0064] starting on line 6 and ending on line 16 of the specification as follows:

[0064] Figures 5a through 5d show the above-described opening procedure in detail. The tool 50, which has two lifting surfaces 52 and 54, is moved at a certain azimuthal position towards the stack 12 of storage rings and then grips under the storage ring 10a with the upper lifting surface. The storage ring 10a is then moved upwards by a certain path until the lower lifting surface touches the storage ring 10b. The lower storage ring 10b is then lifted by a certain path in turn, whereby all the storage rings lying above it are lifted further with it. In this position, the wafer that lies on the storage ring 10b can be accessed, free from elements of the device or other wafers, as this is evident from Figure 5d. Thus, this wafer can now be removed by means of the gripper 60 (see Figure 9). In principle, it is possible to proceed in the same manner for inserting a wafer into the device and for depositing it on the storage ring 10b in

relation to the formation of an access space for the storage ring 10b.